BGA Heat Sink - High Performance Device Specific - NXP

*Image above is for illustration purpose only.

ATS Part#: **ATS-59010-C1-R0**

Description: 62.00 x 52.00 x 13.00 mm BGA Heat Sink - High Performance Device Specific - NXP

Heat Sink Type: NXP

Heat Sink Attachment: maxiGRIP

Equivalent Part Number: N/A

Features & Benefits

- Designed for flip-chip processors such as NXP MPCs
- **maxiGRIP™** attachment applies steady, even pressure to the component and does not require holes in the PCB
- Comes preassembled with high performance, thermal interface material

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	3.2 °C/W	2.6 °C/W	2.1 °C/W	1.9 °C/W	1.7 °C/W	1.5 °C/W	1.4 °C/W
	Ducted Flow	1.8	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish
	62.00 mm	52.00 mm	13.00 mm	52 mm	3M8815	BLACK-ANODIZED

*Image above is for illustration purpose only.

Notes:

- Dimension A and B refer to component size.
- Dimension C is the heat sink height from the bottom of the base to the top of the fin field.
- Thermal performance data are provided for reference only. Actual performance may vary by application.
- ATS reserves the right to update or change its products without notice to improve the design or performance.
- ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant.
- Optional **maxiGRIP™** Installation/Removal Tool Set P/N: **MGT170**
- Contact ATS to learn about custom options available.

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), **sales@qats.com** or **www.qats.com**.

© 2013 Advanced Thermal Solutions, Inc. | 89-27 Access Road | Norwood MA | 02062 | USA

ATS ADVANCED THERMAL SOLUTIONS, INC. Innovations in Thermal Management®

Rev - 230517